Special Issue

Design of Adhesive Bonded Joints

Message from the Guest Editor

The adhesive bonding technology has shown significant improvements over the past few decades, which enabled its application in many industries, such as aerospace, aeronautical and automotive. Experimentally, new adhesives, material combinations, and joint geometries are continuously being explored, leading to innovative designs and improved solutions. On the other hand, analytical and numerical strength prediction models aim to accurately predict the joint's behavior and, as a result, reduce the costs and expedite design. Constant evolution of these models is currently taking place, triggered by the need to model complex materials and loadings, with emphasis to numerical models, including improved fracture modelling by techniques, such as fracture mechanics, cohesive zone models, and the adaptation of recent techniques (including meshless methods). Fatigue and impact loadings are particularly challenging and have recently seen major advances. This Special Issue intends to bring together a significant number of good contributions in this area through high-quality original works in the adhesive joints field.

Guest Editor

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